



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REVISIONS				
		P	LTR	DESCRIPTION	DATE	OWN
AD	00	0		RELEASED PER EC 0512-0235-04	04OCT04	BM

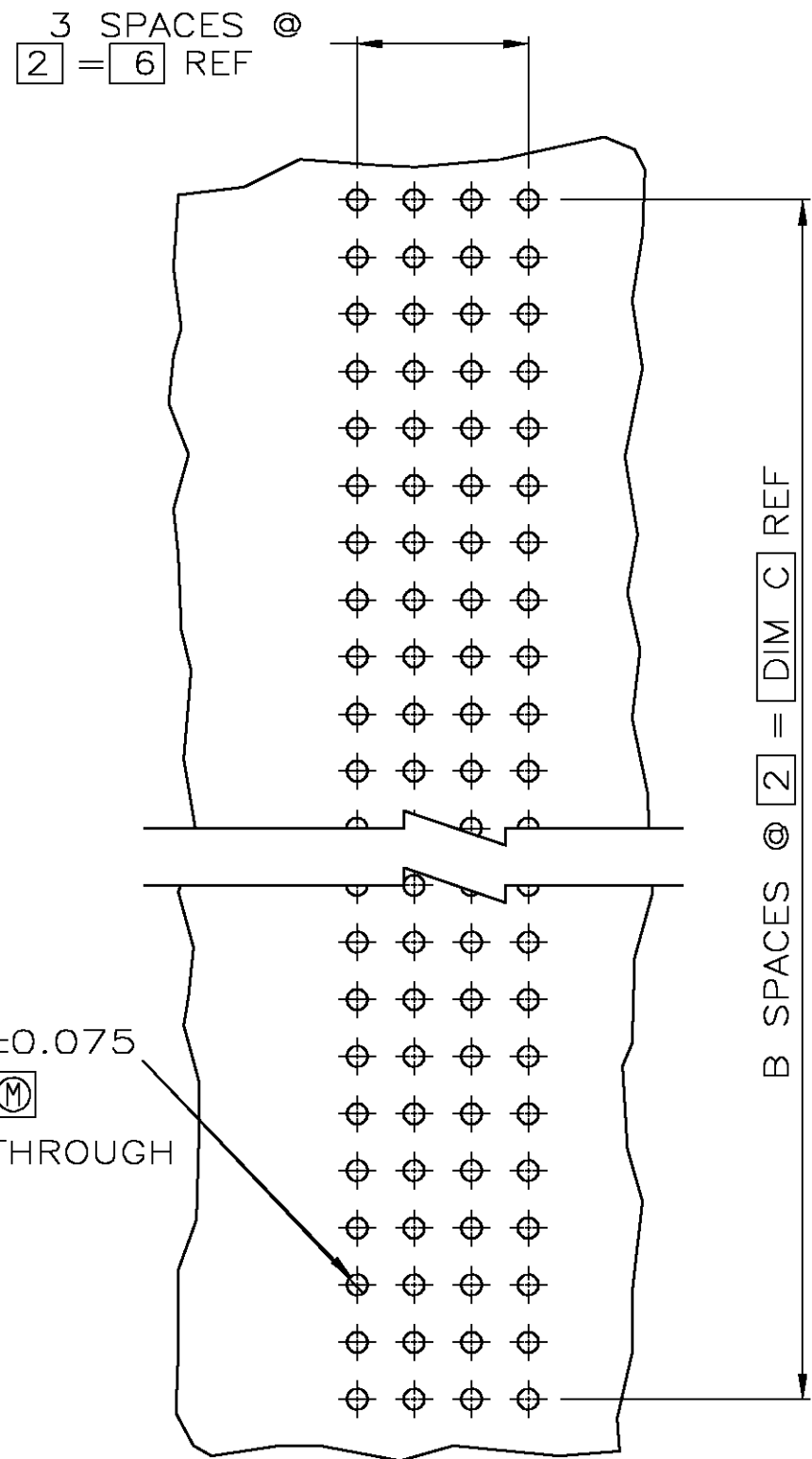
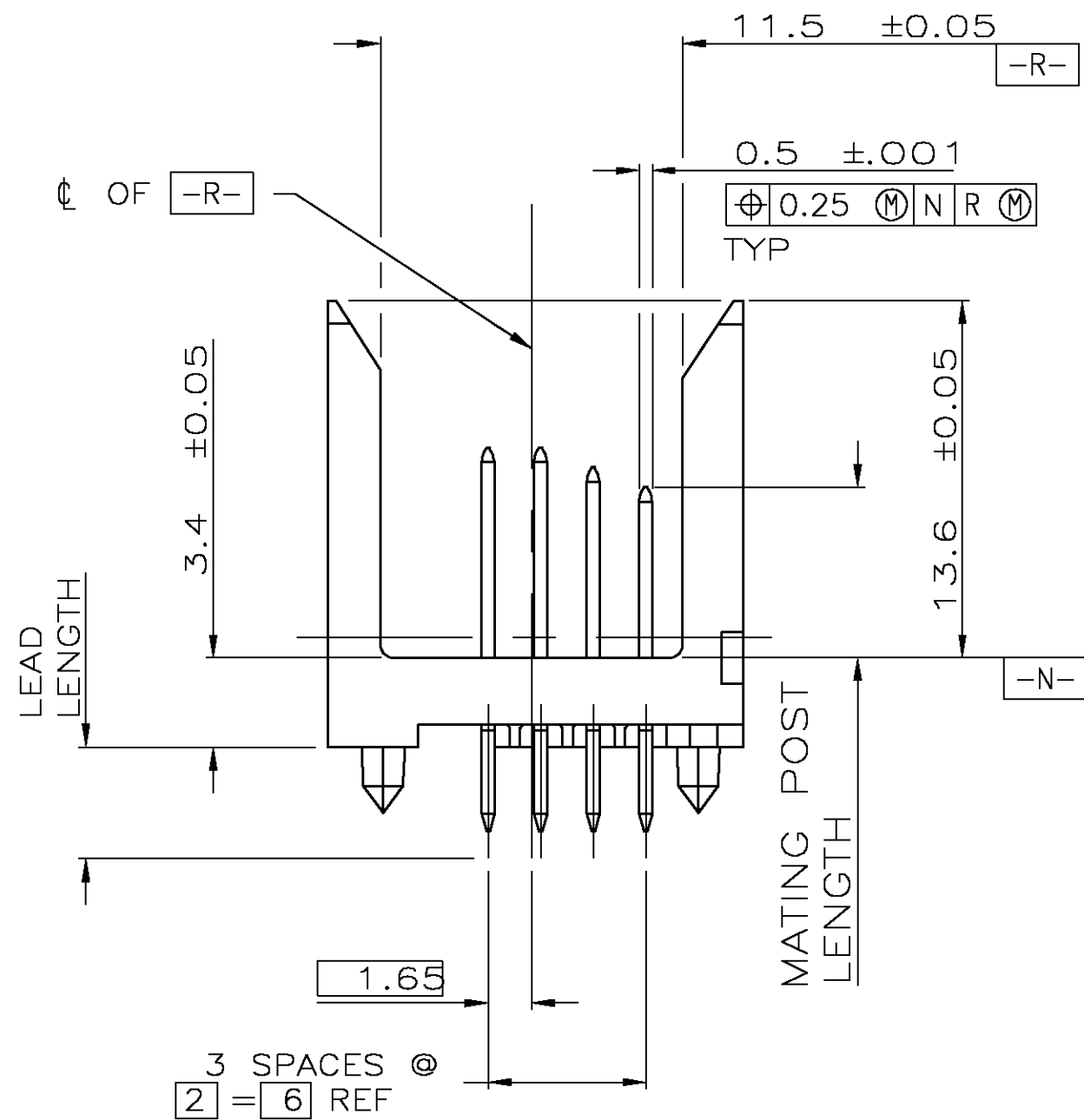
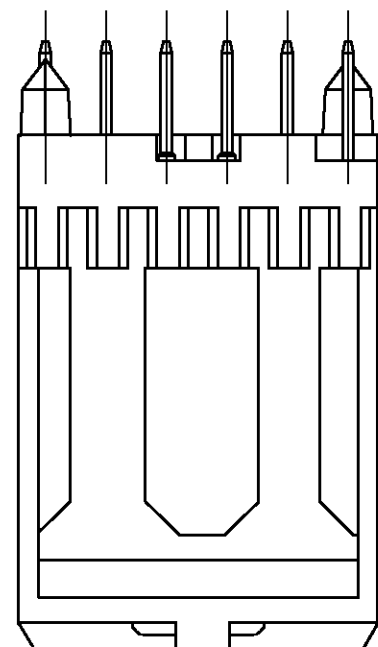
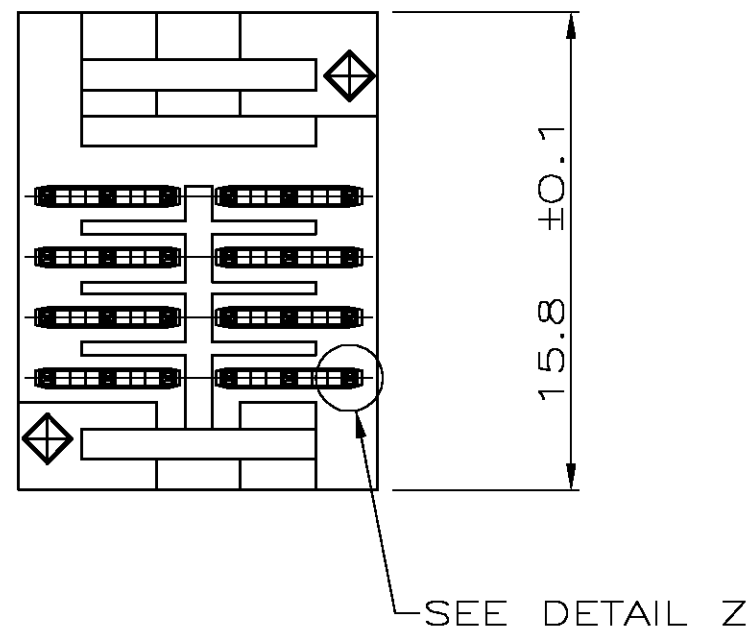
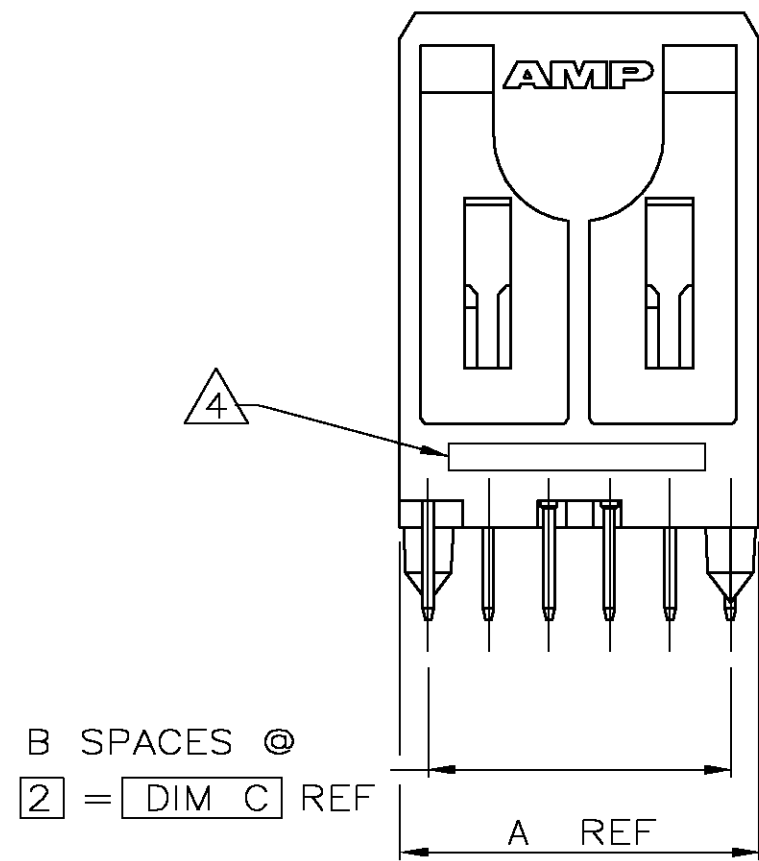
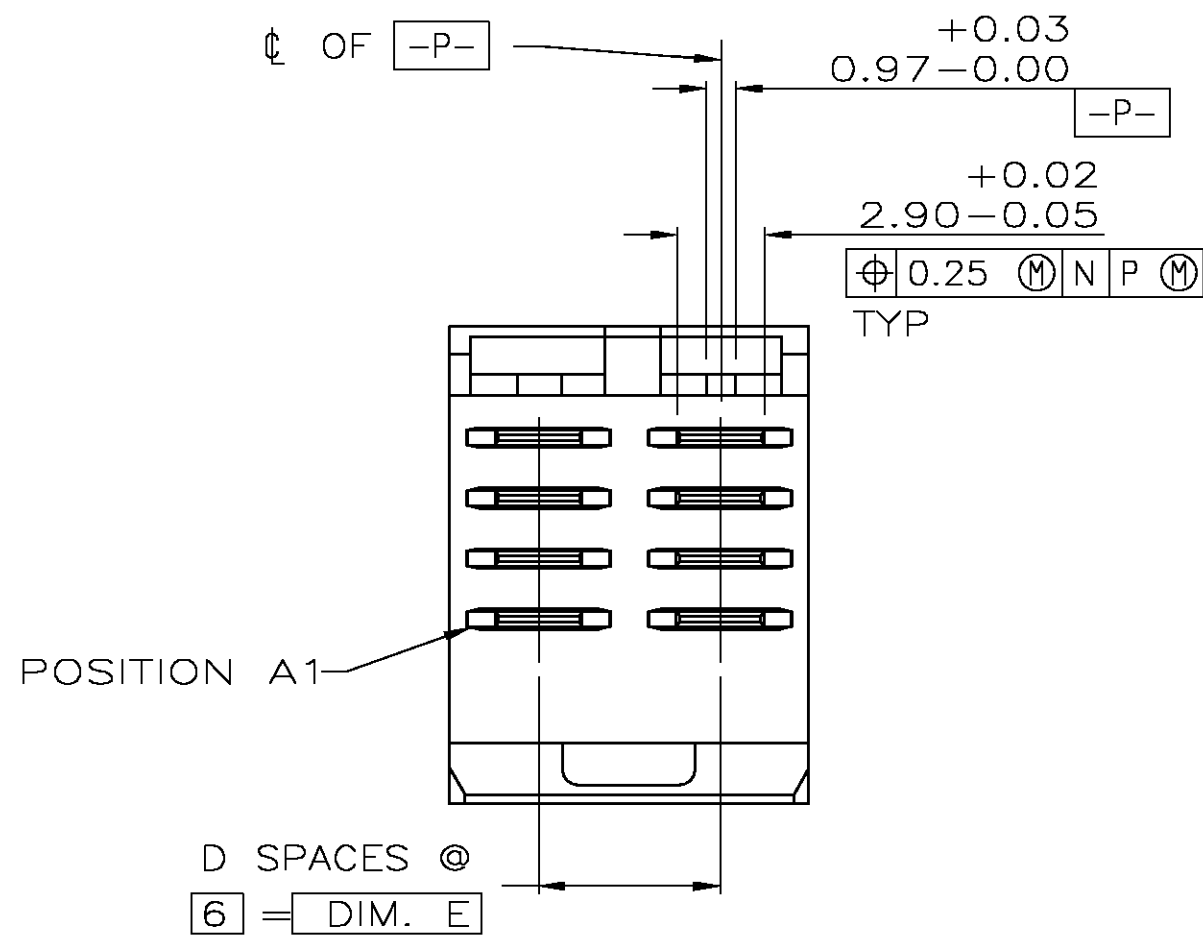
- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER PER ASTM D5138 LCP000 G30A 32250.
- 2 CONTACT MATERIAL: PHOSPHOR BRONZE PER UNS ALLOY NO. C51100, TEMPER: H04.
- 3 CONTACT FINISH:(E)  
UNDERPLATE (ENTIRE CONTACT):  
0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
ON MATING SURFACES:  
FLASH GOLD PER ASTM B 488, OVER  
0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
ON LEADS:  
0.00381 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.  
LUBRICATION (MIN MATING SURFACES):  
SURFACE CONDITIONER AFTER PLATING.
- 4 PART MARKING, LOCATED APPROXIMATELY AS SHOWN.

D

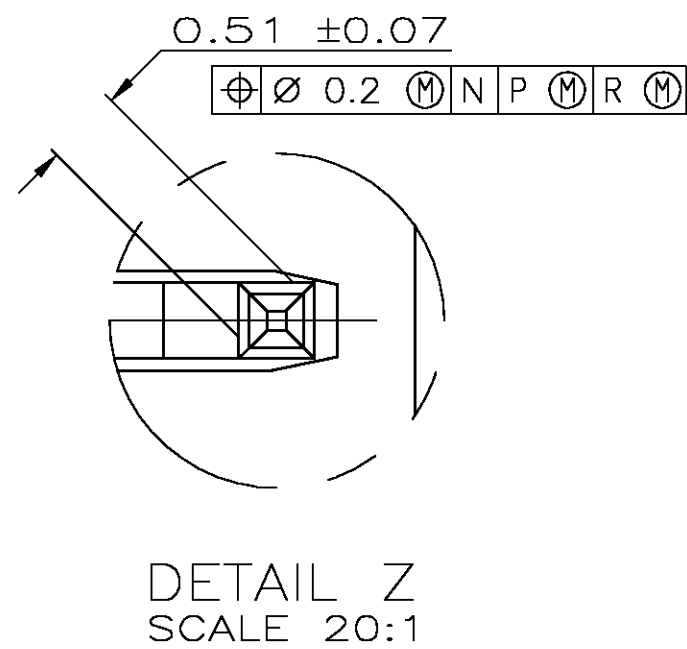
C

B

A



RECOMMENDED CIRCUIT PATTERN  
PER IPC-D300 TYPE II, CLASS C  
(COMPONENT SIDE)



ROW	D	CD	CD
	C	CE	CE
	B	CF	CF
	A	CF	CF
1 2			
POSITION			

CODE LETTER	MATING POST LENGTH $\pm 0.10$	LEAD LENGTH (REF)
CD	6.5	3.2
CE	7.25	3.2
CF	8	3.2

6	1	10	5	11.88	3	8	5536621-1
E	D	C	B	A	FINISH	NO OF POSN	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.				Tyco Electronics Corporation			
DIMENSIONS: INCHES				NAME: PIN ASSEMBLY, POWER MODULE, Z-PACK 2mm FB, 2mm FB, SEQUENCED, BY ROW, SOLDER LEADS			
TOLERANCES UNLESS OTHERWISE SPECIFIED:				SIZE: A1			
MATERIAL				WEIGHT			
FINISH				CUSTOMER DRAWING			
SCALE: 4:1				SHEET 1 OF 1			
REV 0							